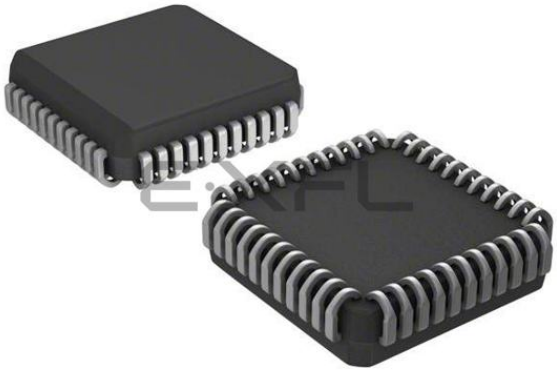

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Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf74t-i-l

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1.0 DEVICE OVERVIEW

This document contains device specific information about the following devices:

- PIC16F73
- PIC16F74
- PIC16F76
- PIC16F77

PIC16F73/76 devices are available only in 28-pin packages, while PIC16F74/77 devices are available in 40-pin and 44-pin packages. All devices in the PIC16F7X family share common architecture, with the following differences:

- The PIC16F73 and PIC16F76 have one-half of the total on-chip memory of the PIC16F74 and PIC16F77
- The 28-pin devices have 3 I/O ports, while the 40/44-pin devices have 5
- The 28-pin devices have 11 interrupts, while the 40/44-pin devices have 12
- The 28-pin devices have 5 A/D input channels, while the 40/44-pin devices have 8
- The Parallel Slave Port is implemented only on the 40/44-pin devices

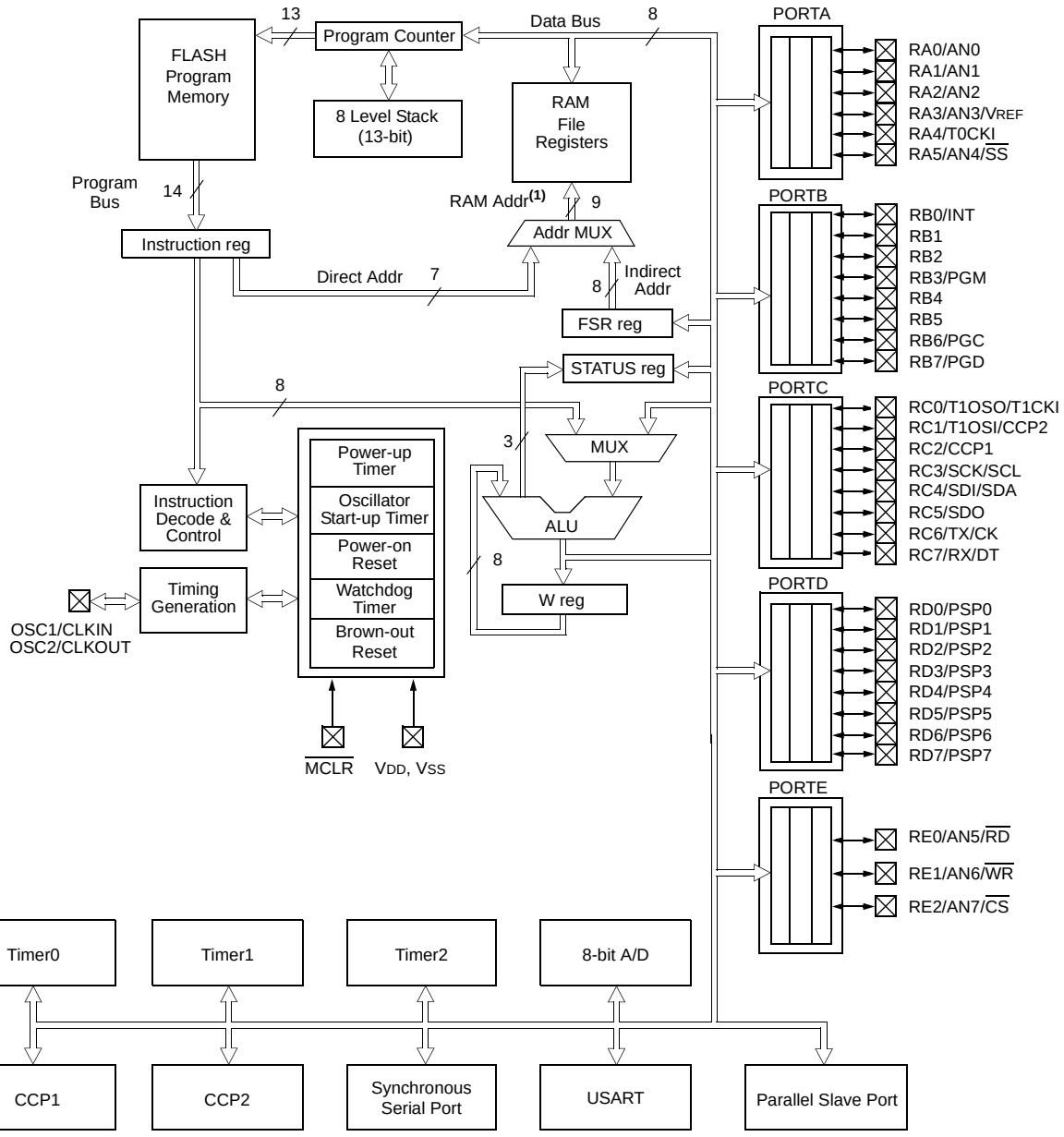
The available features are summarized in Table 1-1. Block diagrams of the PIC16F73/76 and PIC16F74/77 devices are provided in Figure 1-1 and Figure 1-2, respectively. The pinouts for these device families are listed in Table 1-2 and Table 1-3.

Additional information may be found in the PICmicro™ Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip website. The Reference Manual should be considered a complementary document to this data sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

TABLE 1-1: PIC16F7X DEVICE FEATURES

Key Features	PIC16F73	PIC16F74	PIC16F76	PIC16F77
Operating Frequency	DC - 20 MHz	DC - 20 MHz	DC - 20 MHz	DC - 20 MHz
RESETS (and Delays)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)	POR, BOR (PWRT, OST)
FLASH Program Memory (14-bit words)	4K	4K	8K	8K
Data Memory (bytes)	192	192	368	368
Interrupts	11	12	11	12
I/O Ports	Ports A,B,C	Ports A,B,C,D,E	Ports A,B,C	Ports A,B,C,D,E
Timers	3	3	3	3
Capture/Compare/PWM Modules	2	2	2	2
Serial Communications	SSP, USART	SSP, USART	SSP, USART	SSP, USART
Parallel Communications	—	PSP	—	PSP
8-bit Analog-to-Digital Module	5 Input Channels	8 Input Channels	5 Input Channels	8 Input Channels
Instruction Set	35 Instructions	35 Instructions	35 Instructions	35 Instructions
Packaging	28-pin DIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin PLCC 44-pin TQFP	28-pin DIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin PLCC 44-pin TQFP

FIGURE 1-2: PIC16F74 AND PIC16F77 BLOCK DIAGRAM



Device	Program FLASH	Data Memory
PIC16F74	4K	192 Bytes
PIC16F77	8K	368 Bytes

Note 1: Higher order bits are from the STATUS register.

TABLE 2-1: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Details on page
Bank 2											
100h(4)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	27, 96
101h	TMR0	Timer0 Module Register								xxxx xxxx	45, 96
102h(4)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	26, 96
103h(4)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	19, 96
104h(4)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	27, 96
105h	—	Unimplemented								—	—
106h	PORTB	PORTB Data Latch when written: PORTB pins when read								xxxx xxxx	34, 96
107h	—	Unimplemented								—	—
108h	—	Unimplemented								—	—
109h	—	Unimplemented								—	—
10Ah(1,4)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	21, 96
10Bh(4)	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	23, 96
10Ch	PMDATA	Data Register Low Byte								xxxx xxxx	29, 97
10Dh	PMADR	Address Register Low Byte								xxxx xxxx	29, 97
10Eh	PMDATH	—	—	Data Register High Byte						xxxx xxxx	29, 97
10Fh	PMADRH	—	—	—	Address Register High Byte					xxxx xxxx	29, 97
Bank 3											
180h(4)	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								0000 0000	27, 96
181h	OPTION_REG	$\overline{RBPU}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	20, 44, 96
182h(4)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	26, 96
183h(4)	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	19, 96
184h(4)	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	27, 96
185h	—	Unimplemented								—	—
186h	TRISB	PORTB Data Direction Register								1111 1111	34, 96
187h	—	Unimplemented								—	—
188h	—	Unimplemented								—	—
189h	—	Unimplemented								—	—
18Ah(1,4)	PCLATH	—	—	—	Write Buffer for the upper 5 bits of the Program Counter					---0 0000	21, 96
18Bh(4)	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	23, 96
18Ch	PMCON1	— (6)	—	—	—	—	—	—	RD	1--- ---0	29, 97
18Dh	—	Unimplemented								—	
18Eh	—	Reserved maintain clear								0000 0000	
18Fh	—	Reserved maintain clear								0000 0000	

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved.
Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8>, whose contents are transferred to the upper byte of the program counter during branches (CALL or GOTO).

2: Other (non power-up) RESETS include external RESET through $\overline{MCLR}$ and Watchdog Timer Reset.

3: Bits PSPIE and PSPIF are reserved on the 28-pin devices; always maintain these bits clear.

4: These registers can be addressed from any bank.

5: PORTD, PORTE, TRISD, and TRISE are not physically implemented on the 28-pin devices, read as '0'.

6: This bit always reads as a '1'.

2.2.2.8 PCON Register

The Power Control (PCON) register contains flag bits to allow differentiation between a Power-on Reset (POR), a Brown-out Reset (BOR), a Watchdog Reset (WDT) and an external MCLR Reset.

Note:	$\overline{BOR}$ is unknown on POR. It must be set by the user and checked on subsequent RESETS to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is not predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the configuration word).

REGISTER 2-8: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-1
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR reset	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.0 I/O PORTS

Some pins for these I/O ports are multiplexed with an alternate function for the peripheral features on the device. In general, when a peripheral is enabled, that pin may not be used as a general purpose I/O pin.

Additional information on I/O ports may be found in the PICmicro™ Mid-Range Reference Manual, (DS33023).

4.1 PORTA and the TRISA Register

PORTA is a 6-bit wide, bi-directional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= '1') will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a Hi-Impedance mode). Clearing a TRISA bit (= '0') will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, the value is modified and then written to the port data latch.

Pin RA4 is multiplexed with the Timer0 module clock input to become the RA4/T0CKI pin. The RA4/T0CKI pin is a Schmitt Trigger input and an open drain output. All other PORTA pins have TTL input levels and full CMOS output drivers.

Other PORTA pins are multiplexed with analog inputs and analog VREF input. The operation of each pin is selected by clearing/setting the control bits in the ADCON1 register (A/D Control Register1).

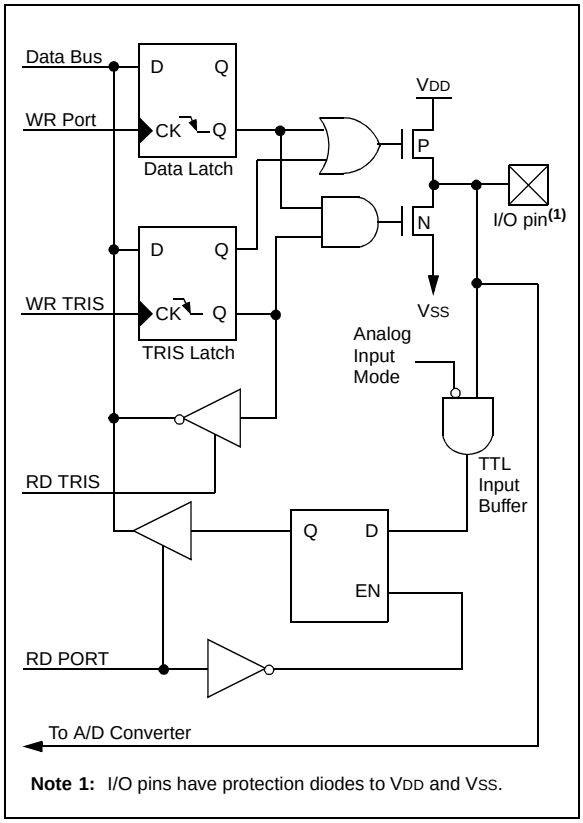
Note:	On a Power-on Reset, these pins are configured as analog inputs and read as '0'.

The TRISA register controls the direction of the RA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA register are maintained set, when using them as analog inputs.

EXAMPLE 4-1: INITIALIZING PORTA

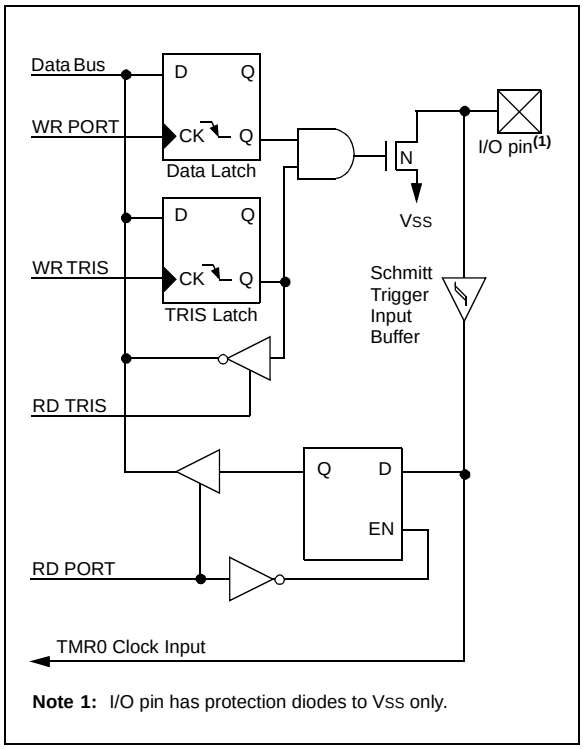
```
BCF     STATUS, RP0   ;
BCF     STATUS, RP1   ; Bank0
CLRF    PORTA         ; Initialize PORTA by
                      ; clearing output
                      ; data latches
BSF     STATUS, RP0   ; Select Bank 1
MOVLW   0x06          ; Configure all pins
MOVWF   ADCON1        ; as digital inputs
MOVLW   0xCF          ; Value used to
                      ; initialize data
                      ; direction
MOVWF   TRISA         ; Set RA<3:0> as inputs
                      ; RA<5:4> as outputs
                      ; TRISA<7:6>are always
                      ; read as '0'.
```

FIGURE 4-1: BLOCK DIAGRAM OF RA3:RA0 AND RA5 PINS



Note 1: I/O pins have protection diodes to VDD and VSS.

FIGURE 4-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



Note 1: I/O pin has protection diodes to VSS only.

8.4.1 CCP PIN CONFIGURATION

The user must configure the RC2/CCP1 pin as an output by clearing the TRISC<2> bit.

Note:	Clearing the CCP1CON register will force the RC2/CCP1 compare output latch to the default low level. This is not the PORTC I/O data latch.

8.4.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode if the CCP module is using the compare feature. In Asynchronous Counter mode, the compare operation may not work.

8.4.3 SOFTWARE INTERRUPT MODE

When Generate Software Interrupt mode is chosen, the CCP1 pin is not affected. The CCP1IF or CCP2IF bit is set, causing a CCP interrupt (if enabled).

8.4.4 SPECIAL EVENT TRIGGER

In this mode, an internal hardware trigger is generated, which may be used to initiate an action.

The special event trigger output of CCP1 resets the TMR1 register pair. This allows the CCPR1 register to effectively be a 16-bit programmable period register for Timer1.

The special event trigger output of CCP2 resets the TMR1 register pair and starts an A/D conversion (if the A/D module is enabled).

Note:	The special event trigger from the CCP1 and CCP2 modules will not set interrupt flag bit TMR1IF (PIR1<0>).

TABLE 8-3: REGISTERS ASSOCIATED WITH CAPTURE, COMPARE, AND TIMER1

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other RESETS
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TMR0IE	INTE	RBIE	TMR0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh	PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
8Ch	PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh	PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	---- ---0
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	--00 0000	--uu uuuu
15h	CCPR1L	Capture/Compare/PWM Register1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM Register1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
1Bh	CCPR2L	Capture/Compare/PWM Register2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch	CCPR2H	Capture/Compare/PWM Register2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by Capture and Timer1.

Note 1: The PSP is not implemented on the PIC16F73/76; always maintain these bits clear.

10.3 USART Synchronous Master Mode

In Synchronous Master mode, the data is transmitted in a half-duplex manner (i.e., transmission and reception do not occur at the same time). When transmitting data, the reception is inhibited and vice versa. Synchronous mode is entered by setting bit SYNC (TXSTA<4>). In addition, enable bit SPEN (RCSTA<7>) is set in order to configure the RC6/TX/CK and RC7/RX/DT I/O pins to CK (clock) and DT (data) lines, respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting bit CSRC (TXSTA<7>).

10.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 10-1. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer register TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR is loaded with new data from the TXREG (if available). Once the TXREG register transfers the data to the TSR register (occurs in one TCYCLE), the TXREG is empty and interrupt bit TXIF (PIR1<4>) is set. The interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set, regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit TRMT (TXSTA<1>) shows the status of the TSR register. TRMT is a read only bit, which is set when the TSR is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty. The TSR is not mapped in data memory, so it is not available to the user.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the CK line. Data out is stable around the falling edge of the synchronous clock (Figure 10-6). The transmission can also be started by first loading the TXREG register and then setting bit TXEN (Figure 10-7). This is advantageous when slow baud rates are selected, since the BRG is kept in RESET when bits TXEN, CREN and SREN are clear. Setting enable bit TXEN will start the BRG, creating a shift clock immediately. Normally, when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR, resulting in an empty TXREG. Back-to-back transfers are possible.

Clearing enable bit TXEN during a transmission will cause the transmission to be aborted and will reset the transmitter. The DT and CK pins will revert to hi-impedance. If either bit CREN or bit SREN is set during a transmission, the transmission is aborted and the DT pin reverts to a hi-impedance state (for a reception). The CK pin will remain an output if bit CSRC is set (internal clock). The transmitter logic, however, is not reset, although it is disconnected from the pins. In order to reset the transmitter, the user has to clear bit TXEN. If bit SREN is set (to interrupt an on-going transmission and receive a single word), then after the single word is received, bit SREN will be cleared and the serial port will revert back to transmitting, since bit TXEN is still set. The DT line will immediately switch from Hi-impedance Receive mode to transmit and start driving. To avoid this, bit TXEN should be cleared.

In order to select 9-bit transmission, the TX9 (TXSTA<6>) bit should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG can result in an immediate transfer of the data to the TSR register (if the TSR is empty). If the TSR was empty and the TXREG was written before writing the “new” TX9D, the “present” value of bit TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

1. Initialize the SPBRG register for the appropriate baud rate (Section 10.1).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. If interrupts are desired, set enable bit TXIE.
4. If 9-bit transmission is desired, set bit TX9.
5. Enable the transmission by setting bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.
8. If using interrupts, ensure that GIE and PEIE in the INTCON register are set.

REGISTER 12-1: CONFIGURATION WORD (ADDRESS 2007h)(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/P-1	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
—	—	—	—	—	—	—	BOREN	—	CP0	$\overline{\text{PWRTEN}}$	WDTEN	FOSC1	FOSC0
bit13													bit0

bit 13-7 **Unimplemented:** Read as '1'

bit 6 **BOREN**: Brown-out Reset Enable bit
1 = BOR enabled
0 = BOR disabled

bit 5 **Unimplemented:** Read as '1'

bit 4 **CP0:** FLASH Program Memory Code Protection bit
1 = Code protection off
0 = All memory locations code protected

bit 3 **$\overline{\text{PWRTEN}}$**: Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 2 **WDTEN**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0 **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: The erased (unprogrammed) value of the configuration word is 3FFFh.

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'
- n = Value when device is unprogrammed		u = Unchanged from programmed state

14.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PICmicro MCUs and can be used to develop for this and other PICmicro microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial Programming™ protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

14.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable V_{DD} and V_{PP} supplies, which allow it to verify programmed memory at V_{DD} min and V_{DD} max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In stand-alone mode, the PRO MATE II device programmer can read, verify, or program PICmicro devices. It can also set code protection in this mode.

14.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PICmicro devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

14.11 PICDEM 1 Low Cost PICmicro Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE in-circuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

14.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C™ bus and separate headers for connection to an LCD module and a keypad.

15.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125°C

Storage temperature ..... -65°C to +150°C

Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$. and RA4) ..... -0.3V to (V_{DD} + 0.3V)

Voltage on V_{DD} with respect to V_{SS} ..... -0.3 to +6.5V

Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0 to +13.5V

Voltage on RA4 with respect to Vss ..... 0 to +12V

Total power dissipation **(Note 1)** 1.0W

Maximum current out of V_{SS} pin ..... 300 mA

Maximum current into V_{DD} pin ..... 250 mA

Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ± 20 mA

Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ± 20 mA

Maximum output current sunk by any I/O pin ..... 25 mA

Maximum output current sourced by any I/O pin ..... 25 mA

Maximum current sunk by PORTA, PORTB, and PORTE (combined) **(Note 3)** ..... 200 mA

Maximum current sourced by PORTA, PORTB, and PORTE (combined) **(Note 3)** ..... 200 mA

Maximum current sunk by PORTC and PORTD (combined) **(Note 3)** ..... 200 mA

Maximum current sourced by PORTC and PORTD (combined) **(Note 3)** ..... 200 mA

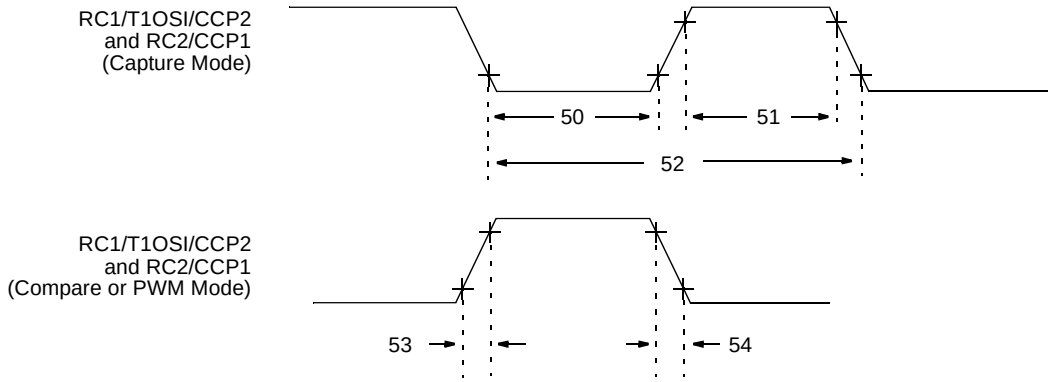
Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

2: Voltage spikes at the $\overline{MCLR}$ pin may cause latchup. A series resistor of greater than 1 kΩ should be used to pull $\overline{MCLR}$ to V_{DD}, rather than tying the pin directly to V_{DD}.

3: PORTD and PORTE are not implemented on the PIC16F73/76 devices.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 15-9: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)



Note: Refer to Figure 15-3 for load conditions.

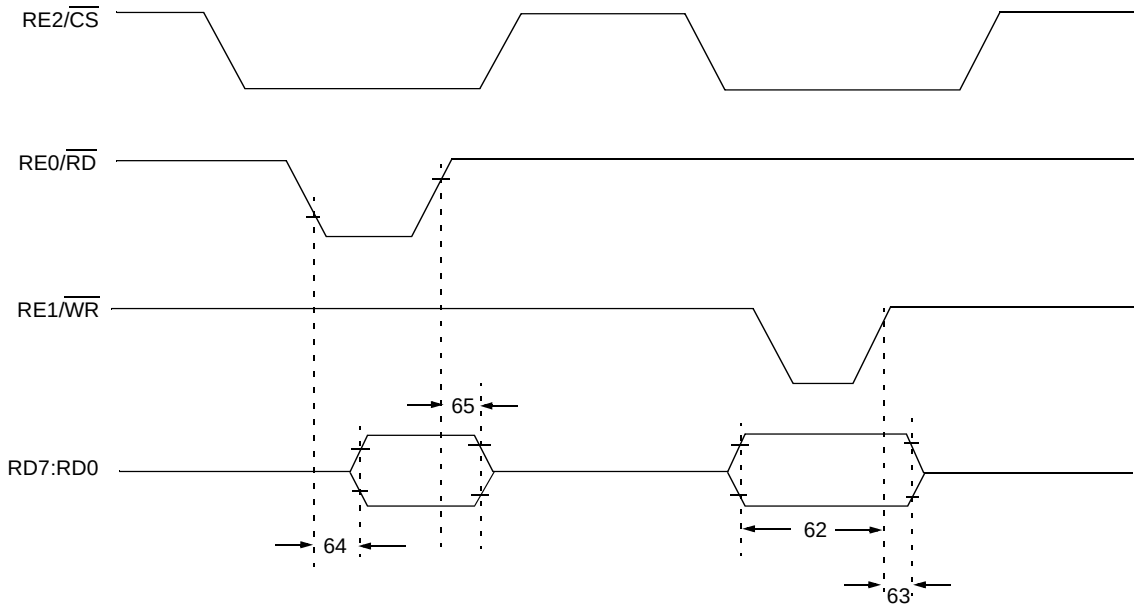
TABLE 15-5: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)

Param No.	Symbol	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard(**F**)	10	—	—	ns	
				Extended(**LF**)	20	—	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler		0.5TCY + 20	—	—	ns	
			With Prescaler	Standard(**F**)	10	—	—	ns	
				Extended(**LF**)	20	—	—	ns	
52*	TccP	CCP1 and CCP2 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 and CCP2 output rise time		Standard(**F**)	—	10	25	ns	
				Extended(**LF**)	—	25	50	ns	
54*	TccF	CCP1 and CCP2 output fall time		Standard(**F**)	—	10	25	ns	
				Extended(**LF**)	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-10: PARALLEL SLAVE PORT TIMING (PIC16F74/77 DEVICES ONLY)



Note: Refer to Figure 15-3 for load conditions.

TABLE 15-6: PARALLEL SLAVE PORT REQUIREMENTS (PIC16F74/77 DEVICES ONLY)

Parameter No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
62	TdtV2wrH	Data in valid before $\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ (setup time)		20 25	— —	— —	ns ns	 Extended range only
63*	TwrH2dtI	$\overline{WR}\uparrow$ or $\overline{CS}\uparrow$ to data in invalid (hold time)	Standard(**F**)	20	—	—	ns	
			Extended(**LF**)	35	—	—	ns	
64	TrdL2dtV	$\overline{RD}\downarrow$ and $\overline{CS}\downarrow$ to data out valid		— —	— —	80 90	ns ns	 Extended range only
65	TrdH2dtI	$\overline{RD}\uparrow$ or $\overline{CS}\downarrow$ to data out invalid		10	—	30	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

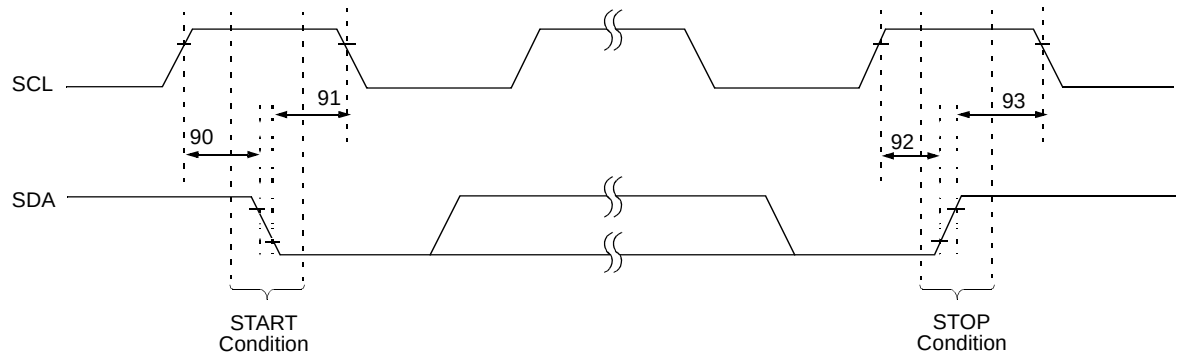
TABLE 15-7: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min	Typ†	Max	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK$\downarrow$ or SCK$\uparrow$ input		TCY	—	—	ns	
71*	TscH	SCK input high time (Slave mode)		TCY + 20	—	—	ns	
72*	TscL	SCK input low time (Slave mode)		TCY + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75*	TdoR	SDO data output rise time	Standard(**F**) Extended(**LF**)	— —	10 25	25 50	ns ns	
76*	TdoF	SDO data output fall time		—	10	25	ns	
77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output hi-impedance		10	—	50	ns	
78*	TscR	SCK output rise time (Master mode)	Standard(**F**) Extended(**LF**)	— —	10 25	25 50	ns ns	
79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	Standard(**F**) Extended(**LF**)	— —	— —	50 145	ns ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge		1.5TCY + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 15-15: I^2C BUS START/STOP BITS TIMING



Note: Refer to Figure 15-3 for load conditions.

TABLE 15-9: I^2C BUS DATA REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Max	Units	Conditions
100*	THIGH	Clock high time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102*	TR	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10 - 400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1CB	300	ns	CB is specified to be from 10 - 400 pF
90*	TSU:STA	START condition setup time	100 kHz mode	4.7	—	µs	Only relevant for Repeated START condition
			400 kHz mode	0.6	—	µs	
91*	THD:STA	START condition hold time	100 kHz mode	4.0	—	µs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	µs	
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	**(Note 2)**
			400 kHz mode	100	—	ns	
92*	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	µs	
			400 kHz mode	0.6	—	µs	
109*	TAA	Output valid from clock	100 kHz mode	—	3500	ns	**(Note 1)**
			400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
	CB	Bus capacitive loading		—	400	pF	

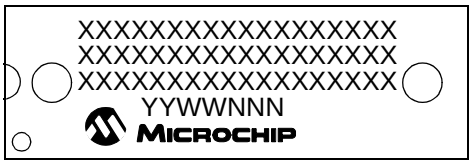
* These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

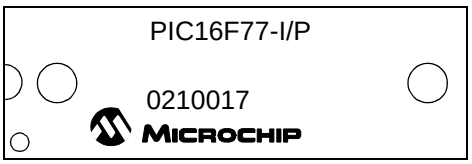
2: A Fast mode (400 kHz) I^2C bus device can be used in a Standard mode (100 kHz) I^2C bus system, but the requirement $T_{SU:DAT} \geq 250$ ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line T_R max. + $T_{SU:DAT}$ = 1000 + 250 = 1250 ns (according to the Standard mode I^2C bus specification), before the SCL line is released.

Package Marking Information (Cont'd)

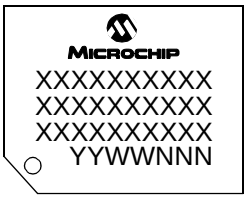
40-Lead PDIP



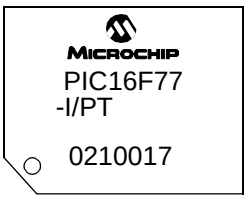
Example



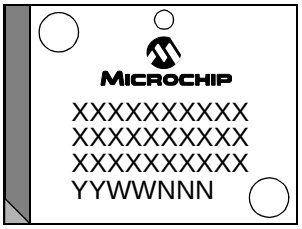
44-Lead TQFP



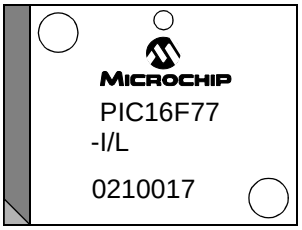
Example



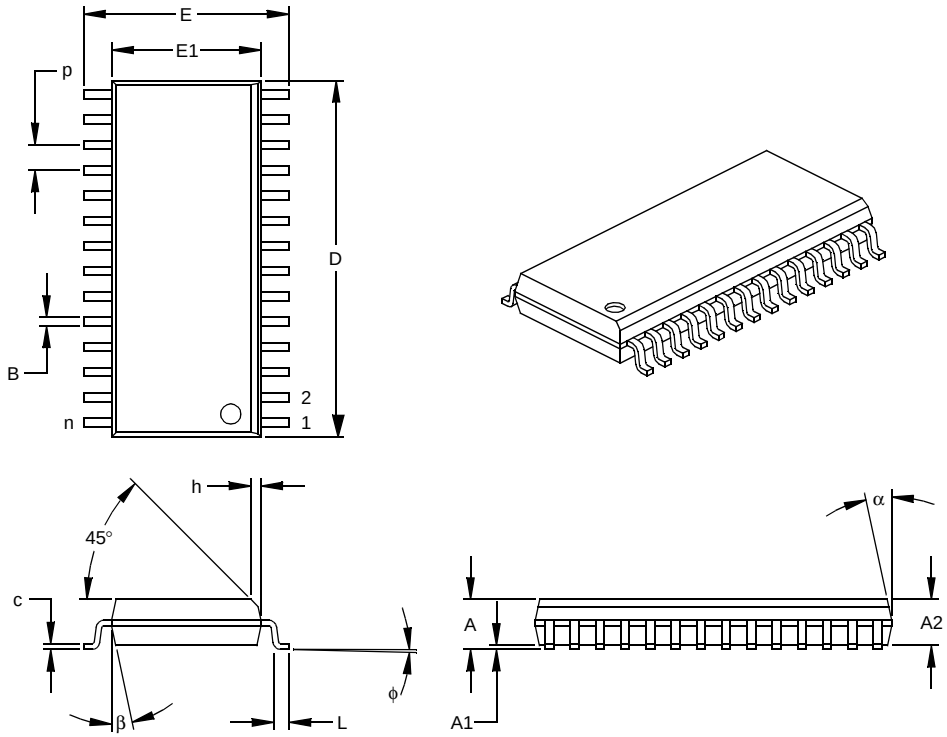
44-Lead PLCC



Example



28-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

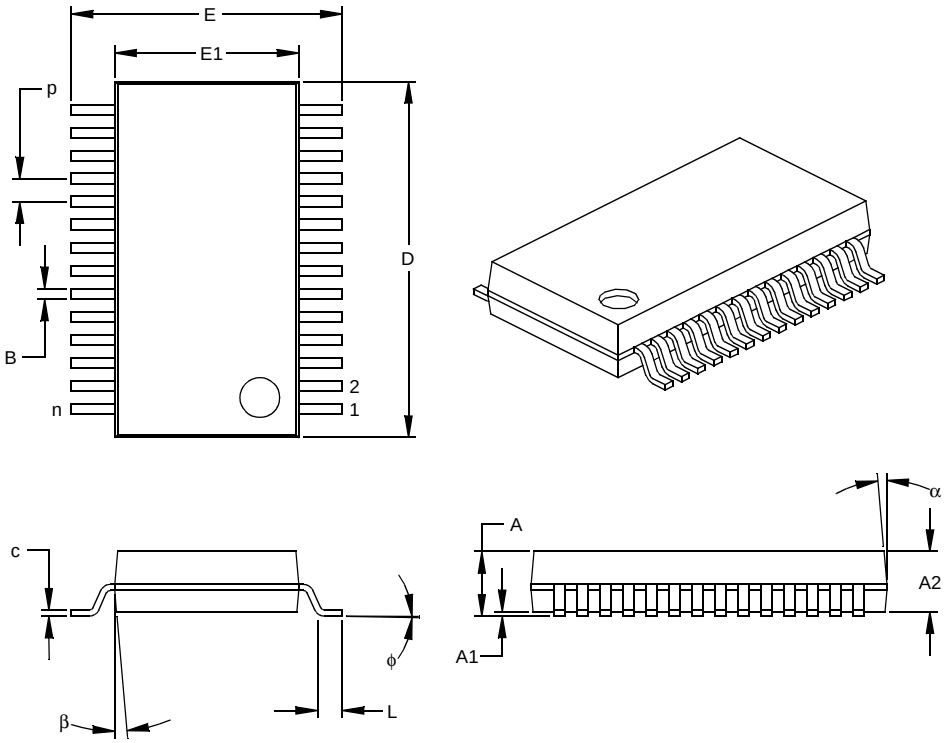


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.013	0.23	0.28	0.33
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-052

28-Lead Plastic Shrink Small Outline (SS) – 209 mil, 5.30 mm (SSOP)

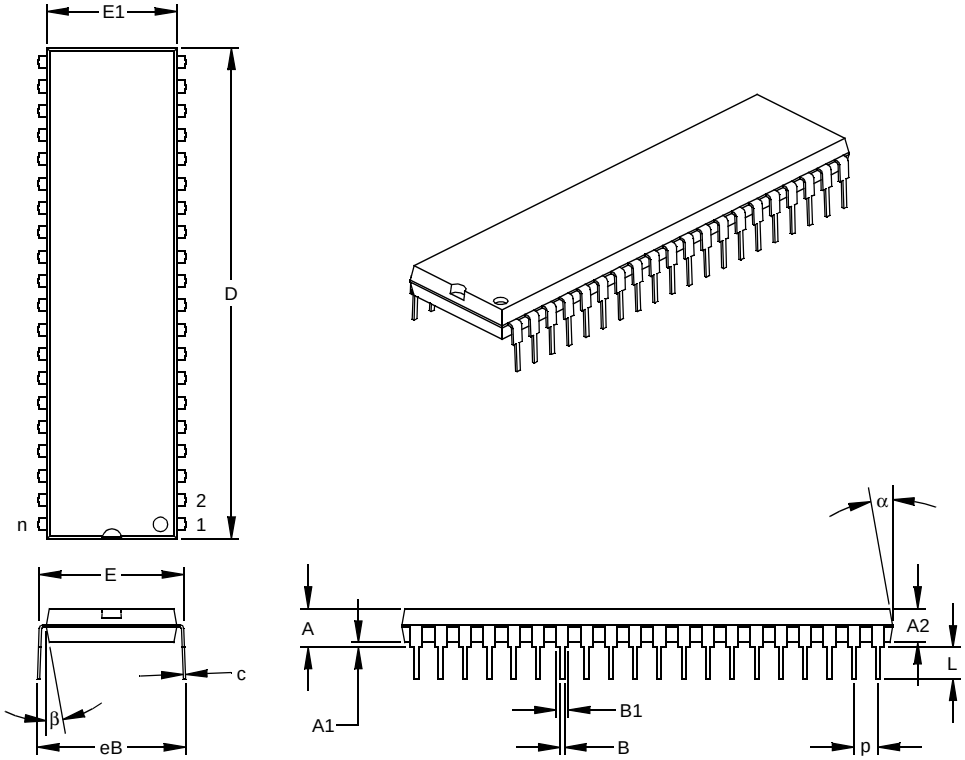


Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.319	7.59	7.85	8.10
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.396	.402	.407	10.06	10.20	10.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-150
Drawing No. C04-073

40-Lead Plastic Dual In-line (P) – 600 mil (PDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		40			40	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.175	.190	4.06	4.45	4.83
Molded Package Thickness	A2	.140	.150	.160	3.56	3.81	4.06
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.595	.600	.625	15.11	15.24	15.88
Molded Package Width	E1	.530	.545	.560	13.46	13.84	14.22
Overall Length	D	2.045	2.058	2.065	51.94	52.26	52.45
Tip to Seating Plane	L	.120	.130	.135	3.05	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.030	.050	.070	0.76	1.27	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing §	eB	.620	.650	.680	15.75	16.51	17.27
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-011
Drawing No. C04-016

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2000	This is a new data sheet. However, these devices are similar to the PIC16C7X devices found in the PIC16C7X Data Sheet (DS30390) or the PIC16F87X devices (DS30292).
B	2001	Final data sheet. Includes device characterization data. Addition of extended temperature devices. Addition of 28-pin MLF package. Minor typographic revisions throughout.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices in this data sheet are listed in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Difference	PIC16F73	PIC16F74	PIC16F76	PIC16F77
FLASH Program Memory (14-bit words)	4K	4K	8K	8K
Data Memory (bytes)	192	192	368	368
I/O Ports	3	5	3	5
A/D	5 channels, 8 bits	8 channels, 8 bits	5 channels, 8 bits	8 channels, 8 bits
Parallel Slave Port	no	yes	no	yes
Interrupt Sources	11	12	11	12
Packages	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin TQFP 44-pin PLCC	28-pin PDIP 28-pin SOIC 28-pin SSOP 28-pin MLF	40-pin PDIP 44-pin TQFP 44-pin PLCC